

S21 LED SMD

PLCC2 5050 RGB

1.Features

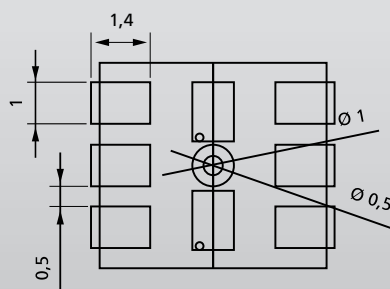
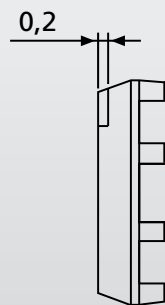
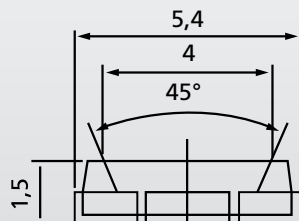
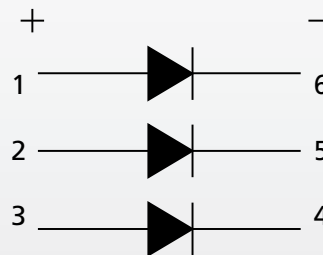
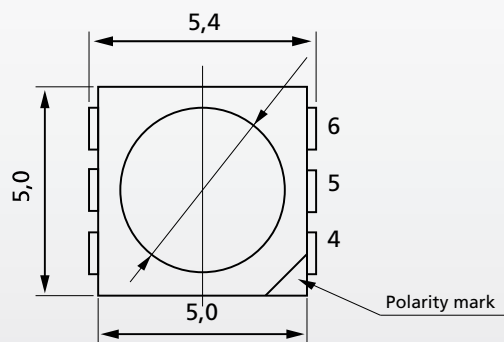
- White package with black surface
- Optical indicator
- Colorless clear window
- Ideal for backlight and light pipe application
- Interior reflector
- Wide viewing angle
- Suitable for vapor-phase reflow, infrared reflow and wave solder processes
- Computable with automatic placement equipment
- Pb-free
- The product itself will remain within RoHS compliant version

2.Applications

- Amusement equipment
- Information boards
- Flashlight for digital camera of cellular phone

Chip		Emitted
Type	Material	
R	A1GaInP	BrilliantRed
G	InGaN	BrilliantGreen
B	InGaN	Blue

2. Package Dimension



Note:
All dimensions in mm tolerance is $\pm 0,1$ mm unless otherwise noted

3. Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit
Power Dissipation	Pd	R	120	mW
		G	110	
		B	110	
Forward Current	I _F	R	50	mA
		G	30	
		B	30	
Peak Forward Current	I _{FP}	R	100	mA
		G	100	
		B	100	
Reverse Voltage	V _R	5		V
Soldering Temperature	Tsol	Reflow Soldering: 260°C for 10 sec Hand Soldering: 350°C for 3 sec		
Operating Temperature	Topr	-40°~90°		Celsius
Storage Temperature	Tstg	-40°~90°		Celsius
Electrostatic discharge	ESD	R	5000	V
		G	2000	
		B	2000	

4. Electrical-optical characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V _f	R	1,8		2,2	V
		G	2,9		3,5	
		B	2,9		3,5	
Luminous Intensity	I _v	R	400		500	mcd
		G	1000		1200	
		B	300		400	
Peak Wavelength	p	R		632		nm
		G		518		
		B		468		
Dominant Wavelength	d	R	625		630	nm
		G	515		522	
		B	460		470	
Spectrum Radiation Bandwidth		R		20		nm
		G		35		
		B		35		
Viewing Angle	20 _{1/2}		120		eg	I _F =20mA
Reverse Current	I _R			5	μA	

BIN range Luminous intensity

Symbol		Bin Code	Min	Max.	Unit	Condition
IV	R	10	270	350	mcd	I _F =20mA
		11	350	460		
		13	600	780		
	G	13	600	780		
		14	780	1000		
		15	1000	1300		
	B	09	210	270		
		10	270	350		
		11	350	460		

BIN range of Dominant Wavelength

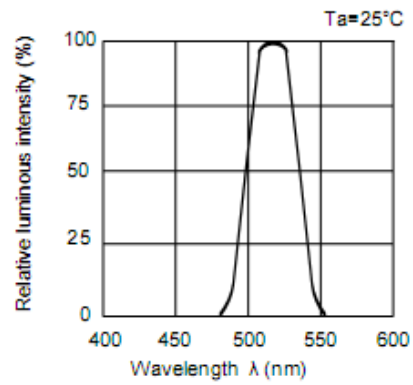
Symbol		Bin Code	Min	Max.	Unit	Condition
λ _d	R	R1	619	625	nm	I _F =20mA
		R2	625	631		
	G	G1	525	530		
		G2	530	535		
	B	B1	465	470		
		B2	470	475		

Note:

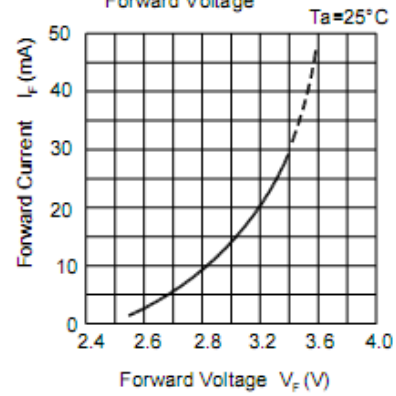
1. Tolerance of Luminous Intensity: ±10%
2. Tolerance of Dominant Wavelength: ±1nm

No.	Test Item	Test Conditions	Sample size	Ac/Re
1	Operation Life	$I_f = 20 \text{ mA}$	22	0/1
2	High Temperature High Humidity	85°C / 85%RH	22	0/1
3	Thermal Shock	H : +100°C 5min § 10 sec L : -10°C 5min	22	0/1
4	High Temperature Storage	Temp. : 100°C	22	0/1
5	Low Temperature Storage	Temp. : -40°C	22	0/1
6	Temperature Cycle	H : +100°C 15min § 5 min L : -40°C 15min	22	0/1
7	Reflow Soldering	Temp. : 260°C ± 5°C Min. 5sec.	22	0/1

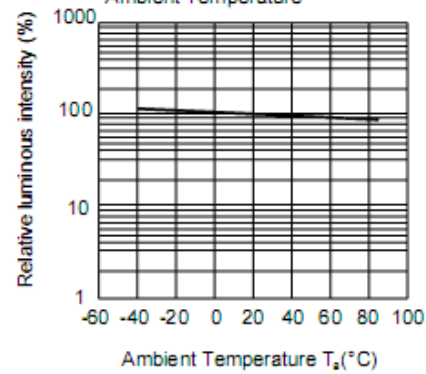
Spectrum Distribution



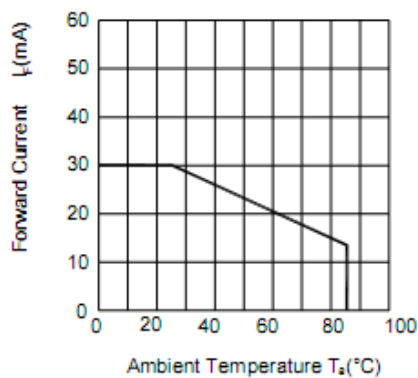
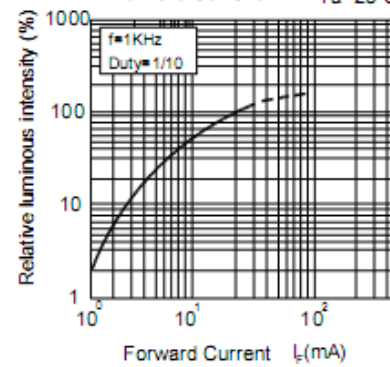
Forward Current vs. Forward Voltage



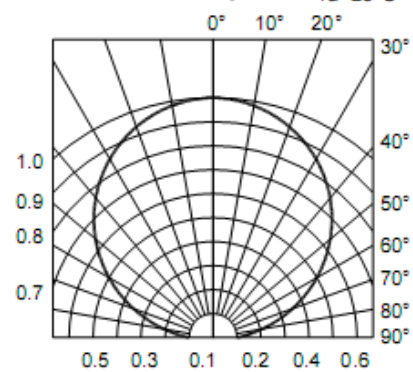
Relative Luminous Intensity vs. Ambient Temperature

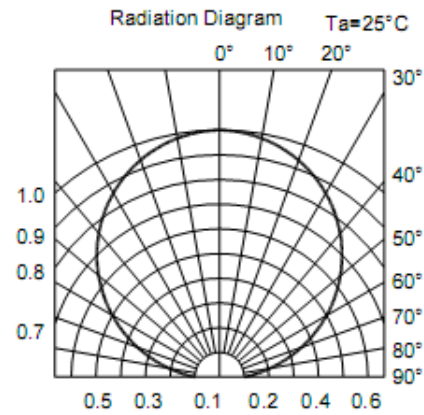
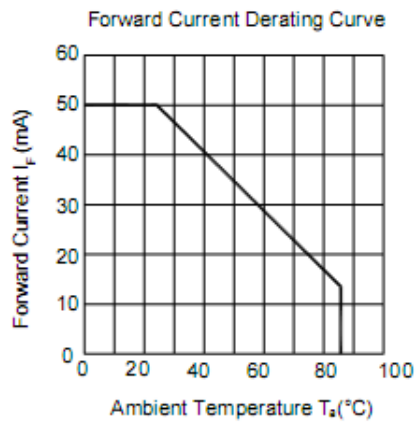
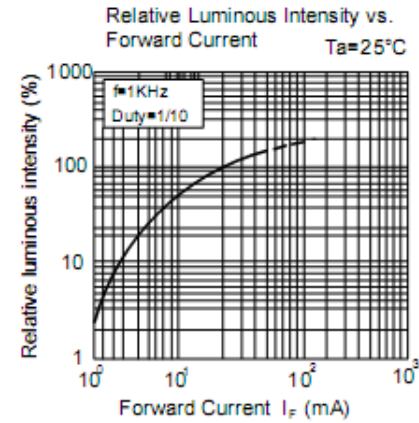
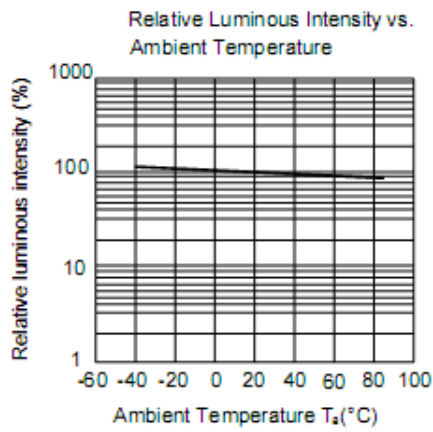
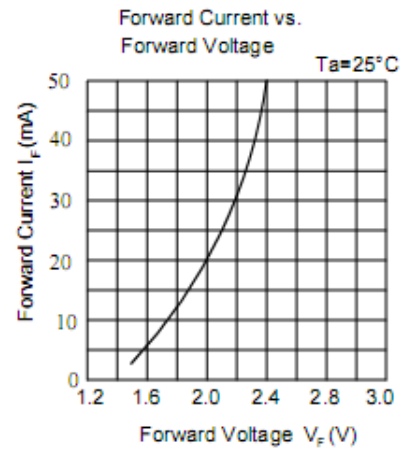
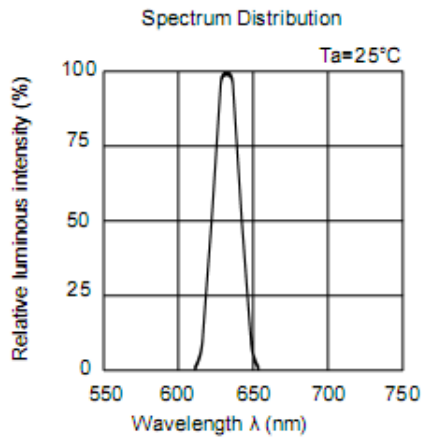


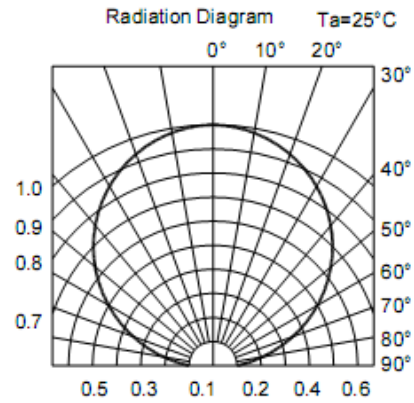
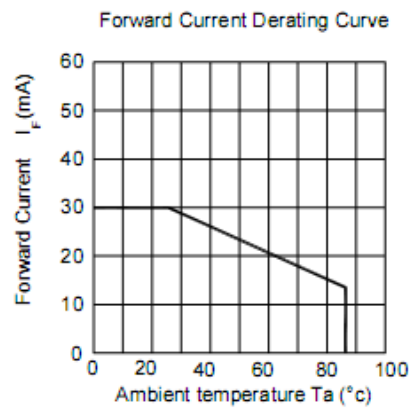
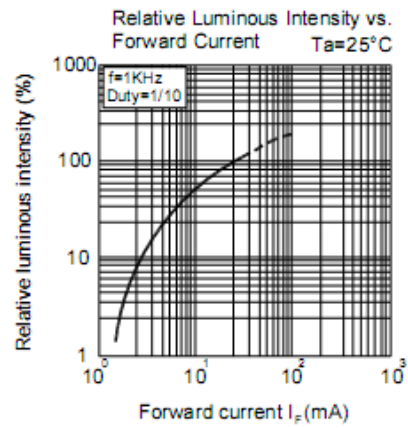
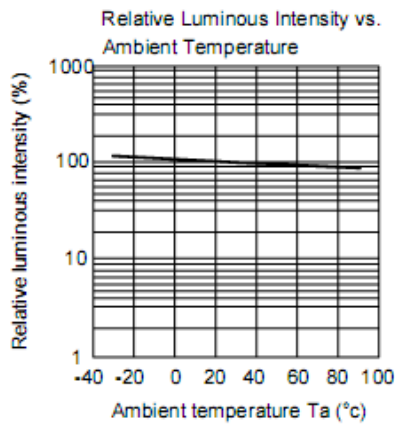
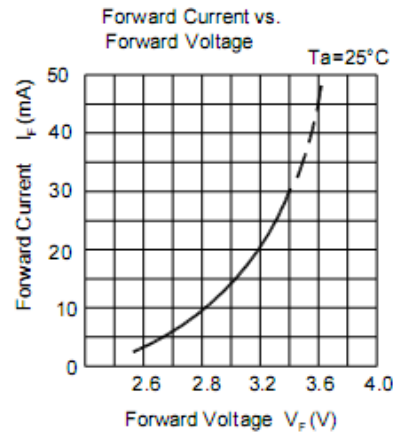
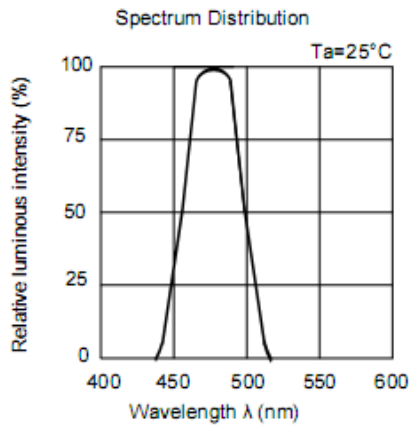
Relative Luminous Intensity vs. Forward Current



Radiation Diagram







Precautions for use :

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30 °C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 °C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5 °C for 24 hours.

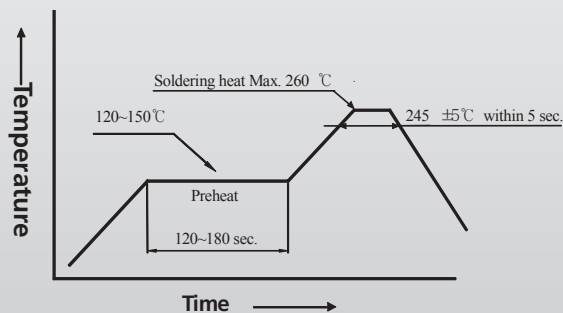
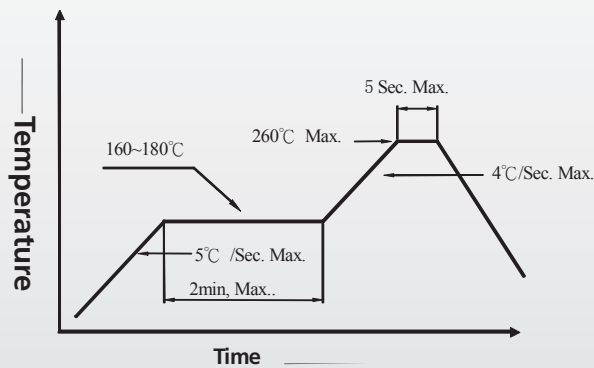
3. Soldering Condition

3.1 Pb-free solder temperature profile

3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

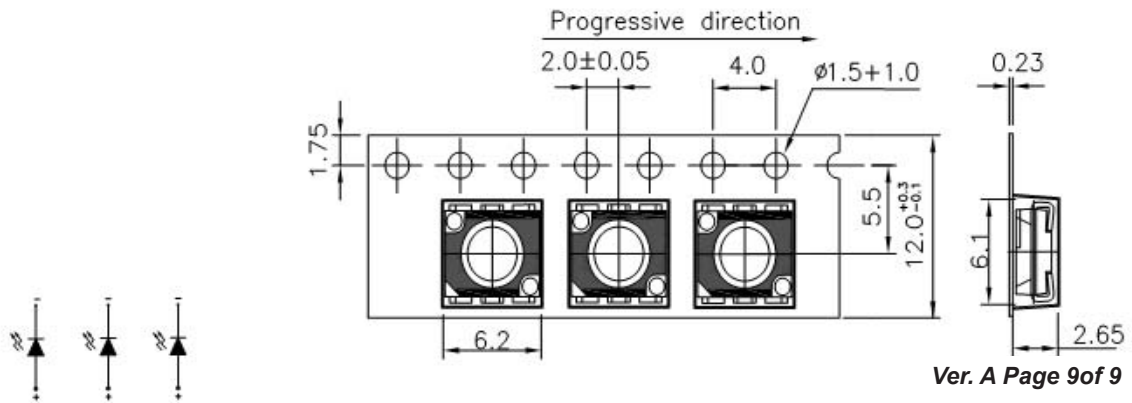


Note: a) Reflow soldering should not be done more than two times.

b) Don't put stress on the LEDs when soldering.

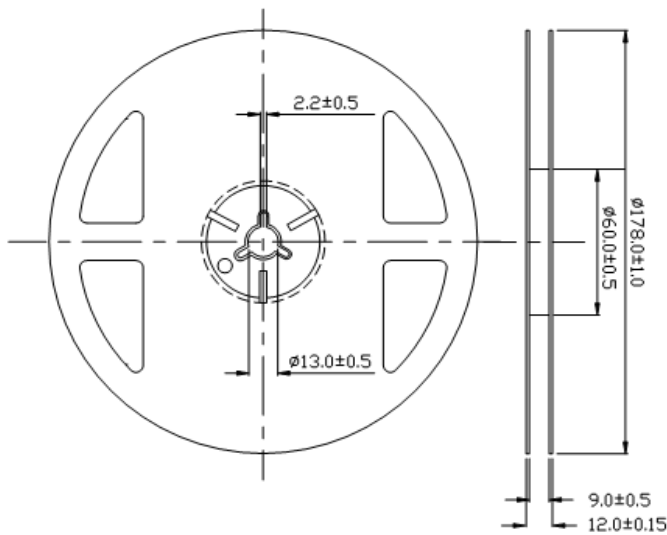
c) Don't warp the circuit board before it have been returned to normal ambient conditions after soldering.

Loaded quantity: 1000 pcs/reel



Note: Tolerance unless mentioned is ± 0.1 mm; Unit = mm

Package Method:(unit:mm)



Note: Tolerance unless mentioned is ± 0.1 mm; Unit = mm